

C1206J225K3RAC

SMD Comm X7R FO, Ceramic, 2.2 uF, 10%, 25 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 1206



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| Т | 1.6mm +/-0.20mm |
| В | 0.6mm +/-0.25mm |

| Packaging Specifications | |
|--------------------------|-----------|
| Packaging | Bulk, Bag |
| Packaging Quantity | 1 |

| General Information | |
|---------------------|--|
| Series | SMD Comm X7R FO |
| Style | SMD Chip |
| Description | SMD, MLCC, Open Mode, Temperature Stable |
| Features | Open Mode, Temperature Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 41 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|--|
| Capacitance | 2.2 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 10% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 227.3 MOhms |

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